



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



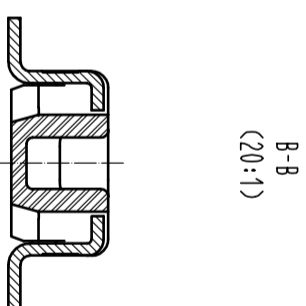
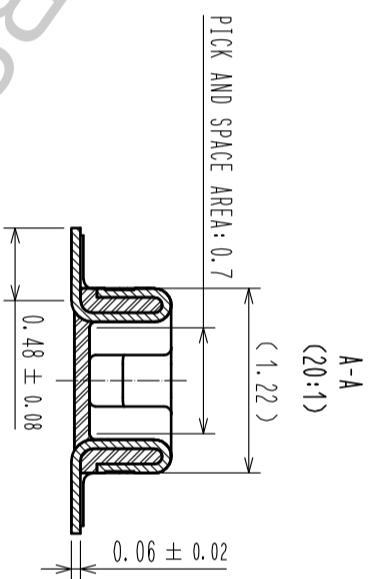
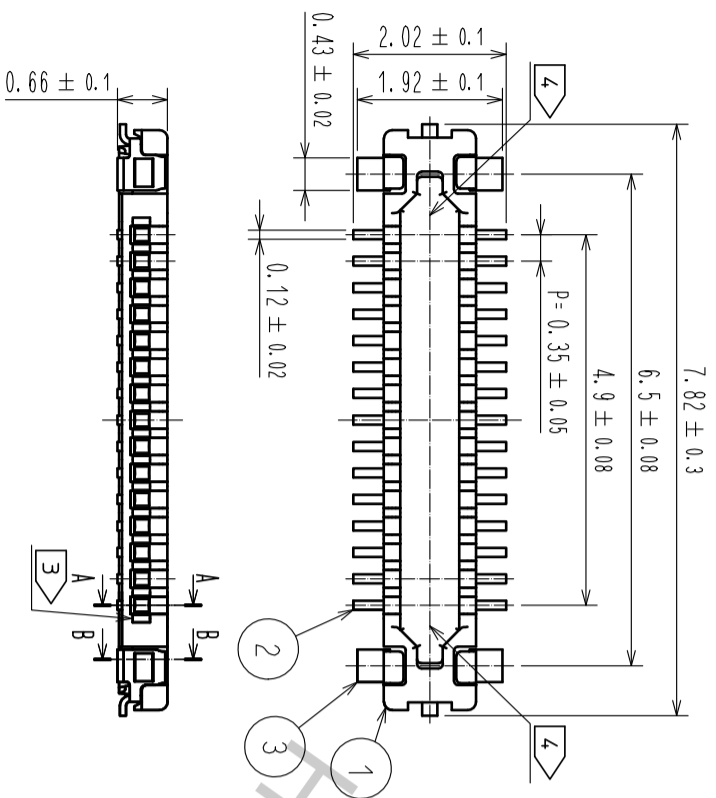
## Contact us

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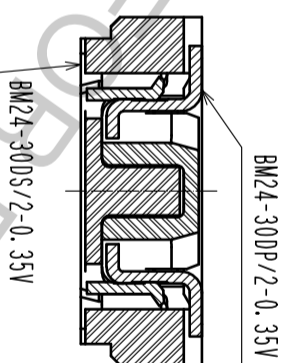
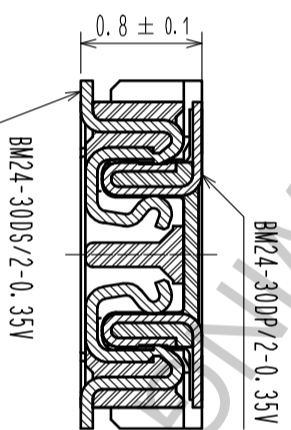
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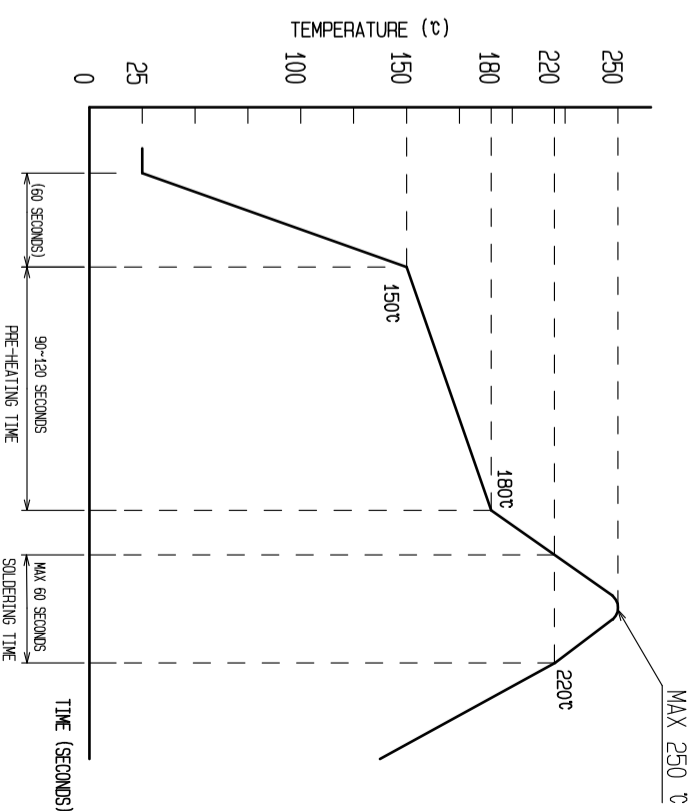




ENGAGEMENT FIGURE (20:1)



5) RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.

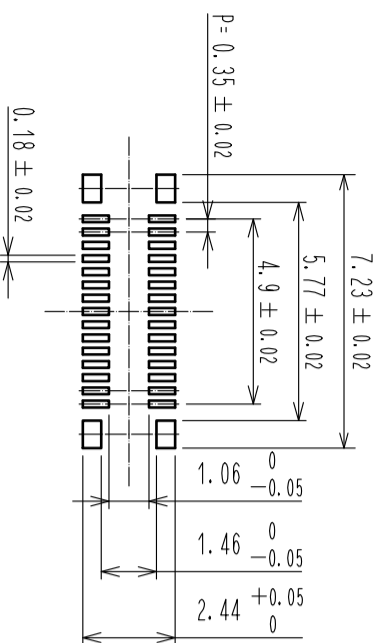


REFLOW METHOD: IR REFLOW  
 NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.  
 1) REFLOW TIME  
 DURATION ABOVE 220°C: 60 SEC MAX.  
 (PEAK TEMPERATURE: 250°C MAX)  
 2) PRE-HEAT TIME  
 PRE-HEAT TEMPERATURE (MIN): 150°C  
 PRE-HEAT TEMPERATURE (MAX): 180°C  
 PRE-HEAT TIME: 90-120 SEC.

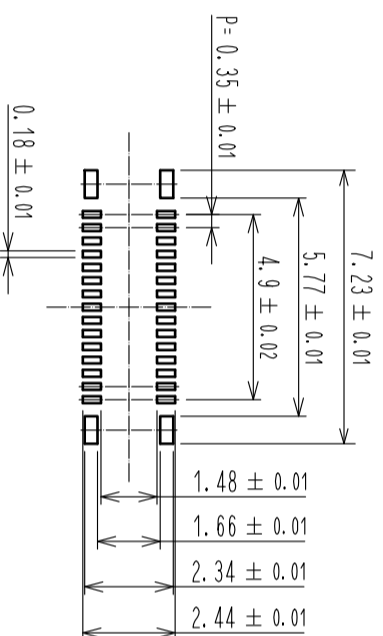
5) THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.  
 6. PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

- NOTE 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
- 2) CONTACT PLATING SPECIFICATIONS  
 CONTACT AREA : GOLD 0.05µm MIN  
 SMT LEAD : GOLD 0.05µm MIN  
 UNDER PLATING : NICKEL 1µm MIN  
 (SURFACE : SEALING)
  - 3) A PART OF THE WALL COULD BE NOTCHED.
  - 4) HRS MARK AND CAV NO. ARE INDICATED IN APPROX. POSITION SHOWN.

◆ RECOMMENDED PCB LAYOUT



◆ RECOMMENDED METAL MASK DIMENSIONS  
 METAL MASK THICKNESS : 100µm



NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
1	LCP	UL94 V-0, BLACK		5	POLYESTER	CLEAR (COVER TAPE)	
2	PHOSPHOR BRONZE	2		6	PS	BLACK (PLASTIC REEL)	
3	COPPER ALLOY	2		7	PS	CLEAR (REINFORCEMENT COLLAR)	
4	PS	CLEAR(EMBOSSED CARRIER TAPE)					

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	10 : 1					

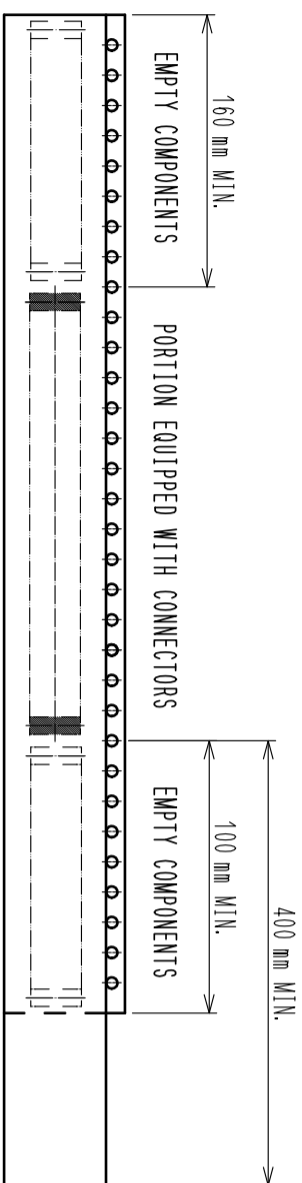
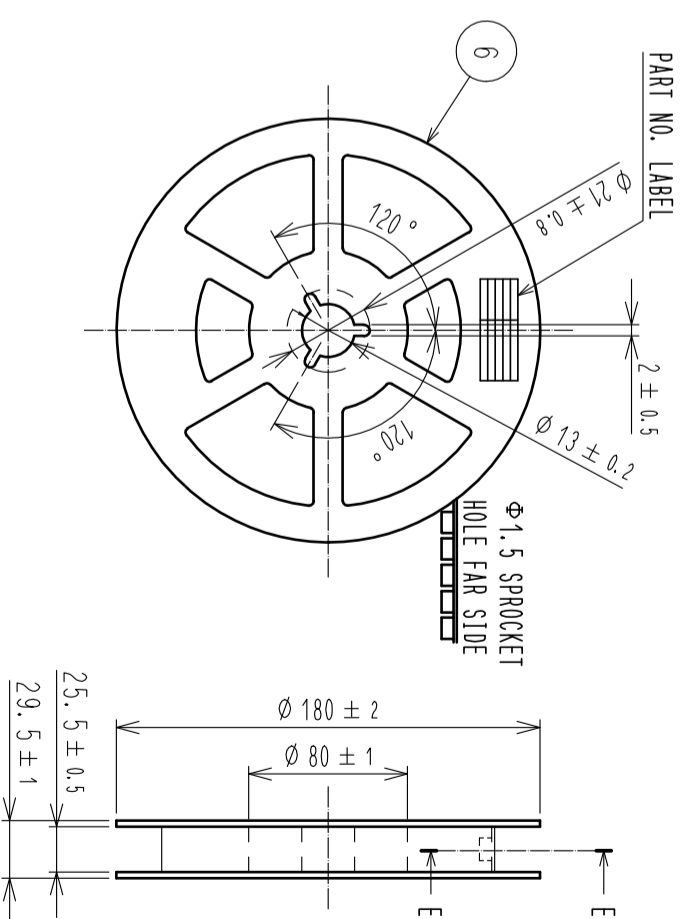
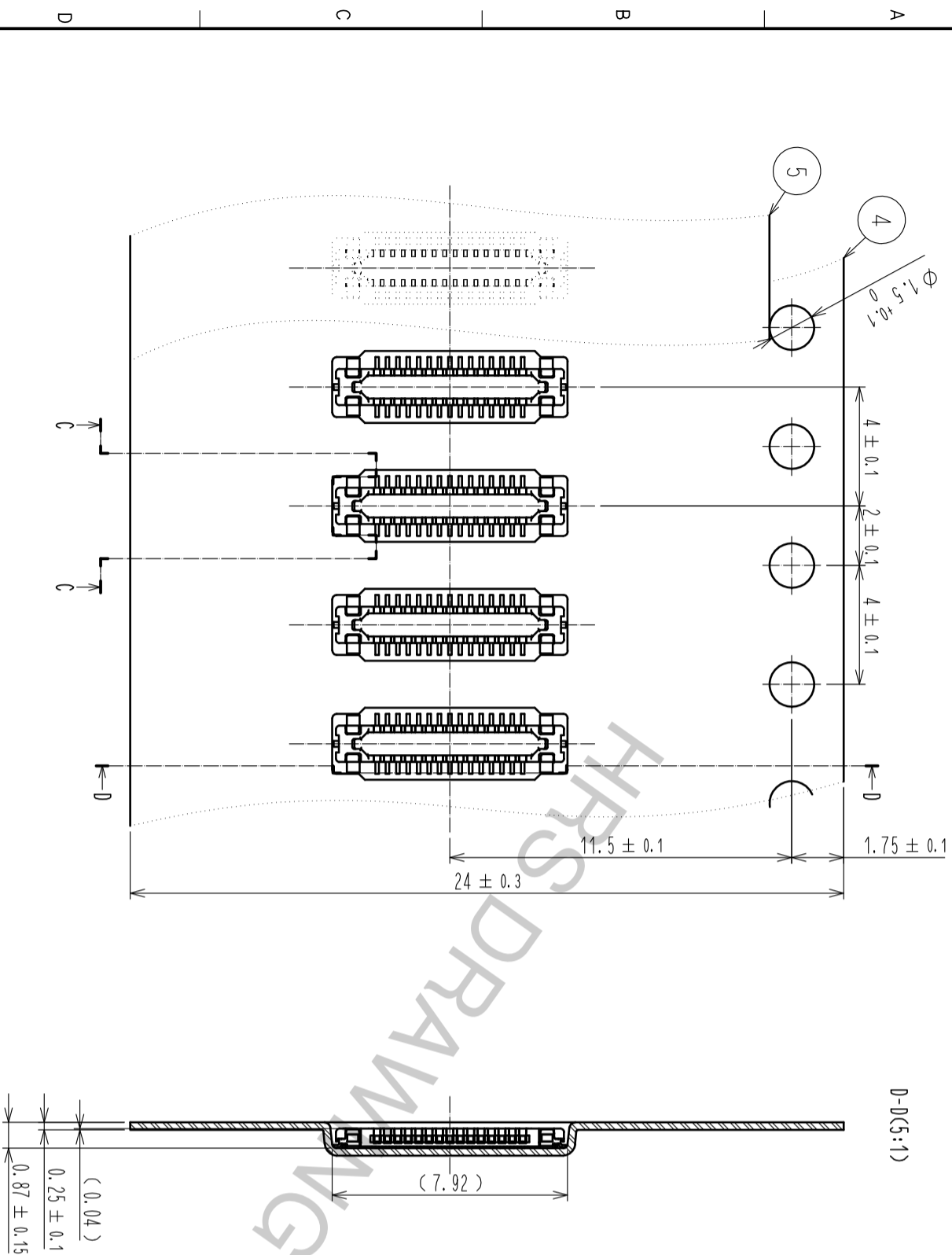
APPROVED	CHECKED	DESIGNED	DRAWN	DRAWING NO.	PART NO.	CODE
MO. ISHIDA	TS. MIYAZAKI	NY. YAMASHIRO	KR. AJITO	15.12.14	15.12.14	15.12.11

EDC-356935-53-01	BM24-30DP/2-0.35V(53)	CL677-2007-5-53

EMBOSSED CARRIER TAPE PACKAGING (FREE)

STYLE AND DIMENTION OF REEL (FREE)



DETAIL OF PART NO. LABEL

製造年月日	*** ** **	DATA OF MANUFACTURED
製品コード	CL0677-2007-5(53)	CODE NO.
製品名	BM24-30DP/2-0.35V(53)	PART NO.
数量	1,000	QUANTITY
納入者	ヒロセ電機(株)	SUPPLIER

7. PER REEL 1,000 CONNECTORS.
8. THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.
9. REFER TO JIS C 0806, IEC 60286-3(PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)
10. AFTER PACKAGING, ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET. AND TAPE DOWN AT THE END THE COLLAR.

TRAILER TAPING(FREE)

LEADER

**HRS**

DRAWING NO.	EDC-356935-53-01
PART NO.	BM24-30DP/2-0.35V(53)
CODE NO.	CL677-2007-5-53